

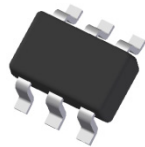
## Features

- IEC 61000-4-2 (ESD): Air  $\pm 15kV$ , Contact  $\pm 8kV$
- 4 Channels of ESD Protection
- Low Channel Input Capacitance of 1.0pF Typical
- Typically Used at High Speed Ports such as USB 2.0, IEEE1394, Serial ATA, DVI, HDMI, PCI
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

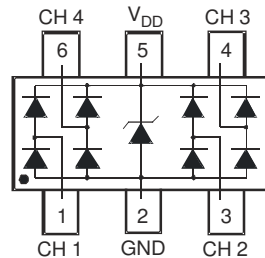
## Mechanical Data

- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Weight: 0.006 grams (approximate)

SOT363



Top View



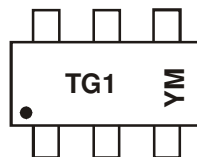
Device Schematic

## Ordering Information (Note 4)

| Product      | Compliance | Marking | Reel size(inches) | Tape width(mm) | Quantity per reel |
|--------------|------------|---------|-------------------|----------------|-------------------|
| DRTR5V0U4S-7 | AEC-Q101   | TG1     | 7                 | 8              | 3,000/Tape & Reel |

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information



TG1 = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: A = 2013)  
 M = Month (ex: 9 = September)

### Date Code Key

| Year | 2013 | 2014 | 2015 | 2016 | 2017 | 2018 | 2019 |
|------|------|------|------|------|------|------|------|
| Code | A    | B    | C    | D    | E    | F    | G    |

| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
|-------|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|-----|
| Code  | 1   | 2   | 3   | 4   | 5   | 6   | 7   | 8   | 9   | O   | N   | D   |

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified)

| Characteristic                     | Symbol                   | Value | Unit | Conditions             |
|------------------------------------|--------------------------|-------|------|------------------------|
| Peak Pulse Current                 | I <sub>PP</sub>          | 5     | A    | 8/20μs, Per Figure 2   |
| ESD Protection – Contact Discharge | V <sub>ESD_Contact</sub> | ±8    | kV   | Standard IEC 61000-4-2 |
| ESD Protection – Air Discharge     | V <sub>ESD_Air</sub>     | ±15   | kV   | Standard IEC 61000-4-2 |

**Thermal Characteristics**

| Characteristic                                   | Symbol                            | Value       | Unit |
|--|-----------------------------------|-------------|------|
| Power Dissipation (Note 5)                       | P <sub>D</sub>                    | 200         | mW   |
| Thermal Resistance, Junction to Ambient (Note 5) | R <sub>θJA</sub>                  | 625         | °C/W |
| Operating and Storage Temperature Range          | T <sub>J</sub> , T <sub>STG</sub> | -65 to +150 | °C   |

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified)

| Characteristic                      | Symbol                 | Min | Typ | Max | Unit | Test Conditions                               |
|-------------------------------------|------------------------|-----|-----|-----|------|---|
| Reverse Standoff Voltage            | V <sub>RWM</sub>       | —   | —   | 5.5 | V    | -   |
| Channel Leakage Current (Note 6, 7) | I <sub>R</sub>         | —   | 1   | 100 | nA   | V <sub>R</sub> = 3V                           |
| Reverse breakdown voltage           | V <sub>BR</sub>        | 6.0 | —   | 9.0 | V    | I <sub>R</sub> = 1mA, from pin 5 to pin 2     |
| Forward Voltage                     | V <sub>F</sub>         | —   | 0.8 | —   | V    | I <sub>F</sub> = 8mA                          |
| Dynamic Resistance                  | R <sub>DYN</sub>       | —   | 0.9 | —   | Ω    | I <sub>PP</sub> = 1A, t <sub>p</sub> = 8/20μs |
| I/O to GND Capacitance              | C <sub>(I/O-GND)</sub> | —   | 1.0 | 1.5 | pF   | V <sub>(I/O-GND)</sub> = 0V, f = 1MHz         |
| I/O to I/O Capacitance              | C <sub>(I/O-I/O)</sub> | —   | 0.6 | —   | pF   | V <sub>(I/O-I/O)</sub> = 0V, f = 1MHz         |

- Notes:
5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com>.
  6. Short duration pulse test used to minimize self-heating effect.
  7. Measured from pin 1, 3, 4, 5 and 6 to GND.
  8. For information on the impact of Diodes' USB 2.0 compatible ESD protectors on signal integrity including eye diagram plots, please refer to AN77 at the following URL: [http://www.diodes.com/destools/appnote\\_dnote.html](http://www.diodes.com/destools/appnote_dnote.html).

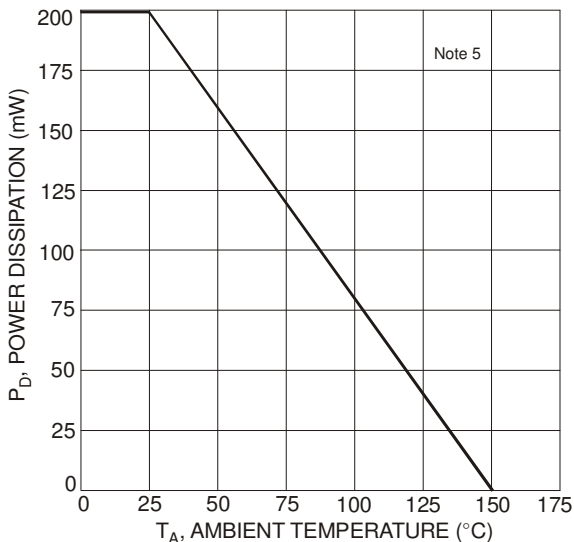


Figure 1 Power Derating Curve

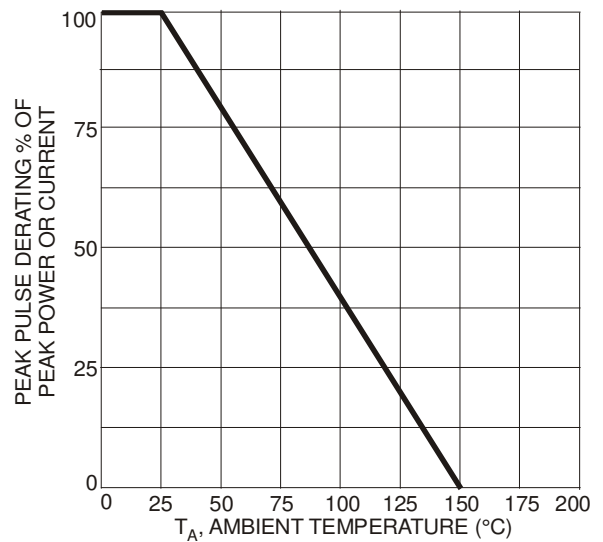


Figure 2 Pulse Derating Curve

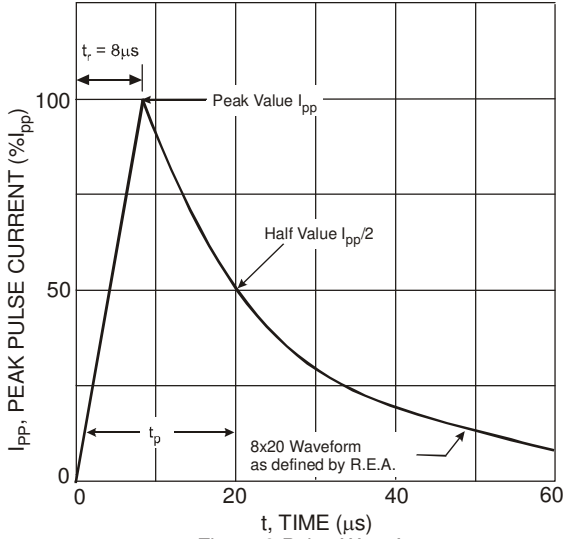


Figure 3 Pulse Waveform

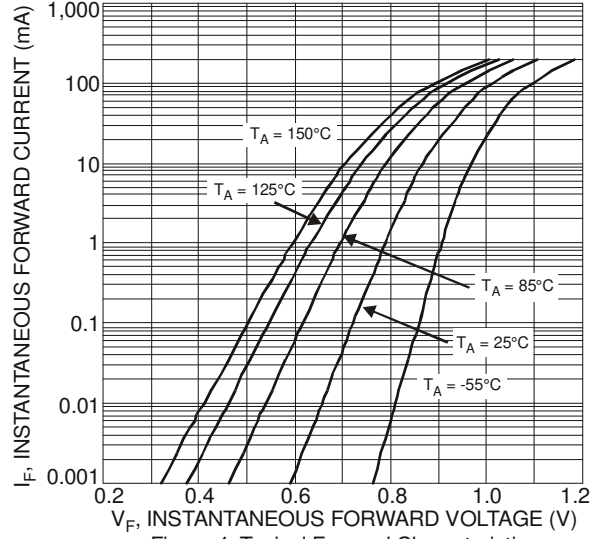


Figure 4 Typical Forward Characteristics

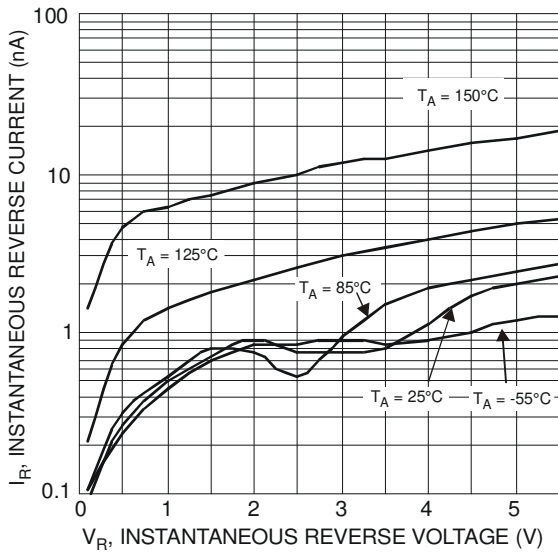


Figure 5 Typical Reverse Characteristics

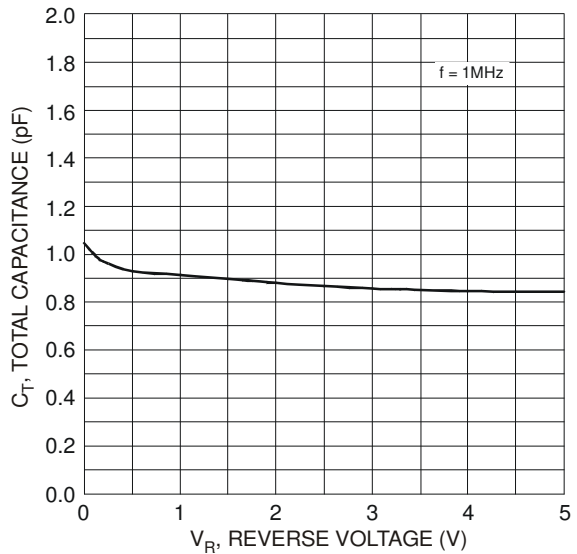
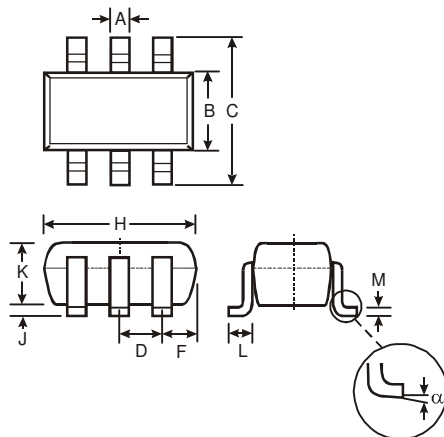


Figure 6 Typical Total Capacitance vs. Reverse Voltage

## Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.

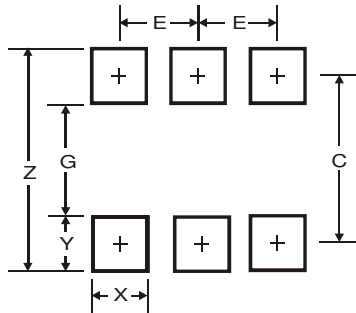


| SOT363   |          |      |       |
|----------|----------|------|-------|
| Dim      | Min      | Max  | Typ   |
| A        | 0.10     | 0.30 | 0.25  |
| B        | 1.15     | 1.35 | 1.30  |
| C        | 2.00     | 2.20 | 2.10  |
| D        | 0.65 Typ |      |       |
| F        | 0.40     | 0.45 | 0.425 |
| H        | 1.80     | 2.20 | 2.15  |
| J        | 0        | 0.10 | 0.05  |
| K        | 0.90     | 1.00 | 1.00  |
| L        | 0.25     | 0.40 | 0.30  |
| M        | 0.10     | 0.22 | 0.11  |
| $\alpha$ | 0°       | 8°   | -     |

All Dimensions in mm

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| Z          | 2.5           |
| G          | 1.3           |
| X          | 0.42          |
| Y          | 0.6           |
| C          | 1.9           |
| E          | 0.65          |

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